

IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (currently amended): A multilayer printed wiring board ~~in which~~ comprising:

 a multilayer core substrate comprising a plurality of insulating layers, a front conductive layer formed on a surface of a front outermost one of the insulating layers, a rear conductive layer formed on a surface of a rear outermost one of the insulating layers, [[an]] a plurality of inner conductive [[layer]] layers formed between the insulating layers, and a plurality of via holes through holes electrically connecting the front, rear and inner conductive layers;

 an interlayer insulation layer formed over the multilayer core substrate;

 a conductive layer formed [[on]] over the interlayer insulating layer and [[over]] the multilayer core substrate ~~composed of front and rear conductive layers and at least a conductive layer as an inner layer and electric connection is performed through via holes,~~

 wherein ~~at least two~~ one of the front[[,]] ~~and~~ rear ~~and inner~~ conductive layers ~~comprise~~ comprises one of a plurality of power source conductive layer layers and a plurality of grounding conductive layer layers, ~~the other one of the front and rear conductive layers~~ comprises the other one of the power source and grounding conductive layers, the plurality of inner conductive layers comprises an inner power source conductive layer and an inner grounding conductive layer, the inner power source conductive layer has a thickness which is larger than a thickness of the power source conductive layer, and the inner grounding conductive layer has a thickness which is larger than a thickness of the grounding conductive layer and ~~at least one of the sum of the thicknesses of the plurality of power source conductive layers in said multilayer core substrate or the sum of the thicknesses of the~~

~~plurality of grounding conductive layers has thicknesses of which a sum is larger than a thickness of the conductive layer on the interlayer insulation layer.~~

Claim 2 (currently amended): The multilayer printed wiring board according to claim 1, wherein ~~assuming that when the a sum of the thicknesses of the power source and inner power source~~ conductive layers in said multilayer core substrate is α_1 , and the ~~a~~ thickness of the conductive layer ~~on the interlayer insulation layer~~ is α_2 , and a relation between α_1 and α_2 [[is]] satisfies $\alpha_2 < \alpha_1 \leq 40\alpha_2$.

Claim 3 (currently amended): The multilayer printed wiring board according to claim 1, wherein ~~assuming that when the a sum of the thicknesses of the grounding and inner grounding~~ conductive layers in said multilayer core substrate is α_3 , and the ~~a~~ thickness of the conductive layer ~~on the interlayer insulation layer~~ is α_2 , and a relation between α_3 and α_2 [[is]] satisfies $\alpha_2 < \alpha_3 \leq 40\alpha_2$.

Claim 4 (currently amended): The multilayer printed wiring board according to claim 1, wherein ~~assuming that when the a sum of the thicknesses of the power source and inner power source~~ conductive layers in said multilayer core substrate is α_1 , and the ~~a~~ thickness of the conductive layer ~~on the interlayer insulation layer~~ is α_2 , and a relation between α_1 and α_2 [[is]] satisfies $1.2\alpha_2 \leq \alpha_1 \leq 40\alpha_2$.

Claim 5 (currently amended): The multilayer printed wiring board according to claim 1, wherein ~~assuming that when the a sum of the thicknesses of the grounding and inner grounding~~ [[layer]] layers in said multilayer core substrate layers is α_3 , and the a thickness thicknesses of the conductive layer layers ~~on the interlayer insulation layer~~ is α_2 , and a relation between α_3 and α_2 [[is]] satisfies $1.2\alpha_2 \leq \alpha_3 \leq 40\alpha_2$.

Claim 6 (currently amended): The multilayer printed wiring board according to claim 1, wherein ~~assuming that when the a sum of the thicknesses of the power source and inner power source~~ conductive layers in said multilayer core substrate is α_1 , and the ~~a~~ thickness of

the conductive layer ~~on the interlayer insulation layer~~ is α_2 , a relation between α_1 and α_2 [[is]] satisfies $\alpha_2 < \alpha_1 \leq 40\alpha_2$, and assuming that when the ~~a~~ sum of the thicknesses of the grounding and inner grounding conductive layers in said multilayer core substrate is α_3 , and a relation between α_3 and α_2 [[is]] satisfies $\alpha_2 < \alpha_3 \leq 40\alpha_2$.

Claim 7 (currently amended): The multilayer printed wiring board according to claim 1, wherein ~~assuming that when the ~~a~~ sum of the thicknesses of the power source and inner power source conductive layers in said multilayer core substrate is α_1 , and the ~~a~~ thickness of the conductive layer ~~on the interlayer insulation layer~~ is α_2 , a relation between α_1 and α_2 [[is]] satisfies $1.2\alpha_2 \leq \alpha_1 \leq 40\alpha_2$, and assuming that when the ~~a~~ sum of the thicknesses of the grounding and inner grounding conductive layers in said multilayer core substrate is α_3 , and a relation between α_3 and α_2 [[is]] satisfies $1.2\alpha_2 \leq \alpha_3 \leq 40\alpha_2$.~~

Claim 8 (canceled)

Claim 9 (withdrawn): A multilayer printed wiring board in which interlayer insulation layer and conductive layer are formed on multilayer core substrate composed of three or more layers, having a plurality of through holes for connecting the front surface with the rear surface and conductive layers on the front and rear surfaces and conductive layer in the inner layer so as to achieve electric connection through via holes,

said a plurality of through holes being composed of a plurality of power source through holes, a plurality of grounding through holes and a plurality of signal through holes connected electrically to a power source circuit or a grounding circuit or a signal circuit of an IC chip,

when said power source through holes pass through the grounding conductive layer of the inner layer in the multilayer core substrate, of the plurality of power source through holes, at least a power source through hole just below the IC having no conductive circuit extending from the power source through hole in the grounding conductive layer.

Claim 10 (withdrawn): A multilayer printed wiring board in which interlayer insulation layer and conductive layer are formed on multilayer core substrate composed of three or more layers, having a plurality of through holes for connecting the front surface with the rear surface and conductive layers on the front and rear surfaces and conductive layer in the inner layer so as to achieve electric connection through via holes,

said a plurality of through holes being composed of a plurality of power source through holes, a plurality of grounding through holes and a plurality of signal through holes connected electrically to a power source circuit or a grounding circuit or a signal circuit of an IC chip,

when said grounding through holes pass through the power source conductive layer of the inner layer in the multilayer core substrate, of the plural grounding through holes, at least a grounding through hole just below the IC having no conductive circuit extending from the grounding through hole in the power source conductive layer.

Claim 11 (withdrawn): A multilayer printed wiring board in which interlayer insulation layer and conductive layer are formed on a multilayer core substrate composed of four or more layers, having a plurality of through holes for connecting the front and rear surfaces and conductive layers on the front and rear surfaces and conductive layer in the inner layer so as to achieve electric connection through via holes,

said multilayer printed wiring board having the power source through holes described in claim 9 .

Claim 12 (withdrawn): A multilayer printed wiring board in which interlayer insulation layer and conductive layer are formed on a multilayer core substrate composed of three or more layers, having a plurality of through holes for connecting the front and rear surfaces and conductive layers on the front and rear surfaces and conductive layer in the inner layer so as to achieve electric connection through via holes,

said a plurality of through holes being composed of a plurality of power source through holes, a plurality of grounding through holes and a plurality of signal through holes connected electrically to a power source circuit or a grounding circuit or a signal circuit of an IC chip,

 when said power source through holes pass through the grounding conductive layer of the inner layer in the multilayer core substrate, of the plurality of power source through holes, 70% or more power source through holes having no conductive circuit extending from the power source through hole in the grounding conductive layer.

 Claim 13 (withdrawn): A multilayer printed wiring board in which interlayer insulation layer and conductive layer are formed on a multilayer core substrate composed of three or more layers, having a plurality of through holes for connecting the front and rear surfaces and conductive layers on the front and rear surfaces and conductive layer in the inner layer so as to achieve electric connection through via holes,

 said a plurality of through holes being composed of a plurality of power source through holes, a plurality of grounding through holes and a plurality of signal through holes connected electrically to a power source circuit or a grounding circuit or a signal circuit of an IC chip,

 when said grounding through holes pass through the power source conductive layer of the inner layer in the multilayer core substrate, of the plurality of grounding through holes, 70% or more grounding through holes having no conductive circuit extending from the grounding through hole in the power source conductive layer.

 Claim 14 (withdrawn): A multilayer printed wiring board in which interlayer insulation layer and conductive layer are formed on a multilayer core substrate composed of four or more layers, having a plurality of through holes for connecting the front and rear

surfaces and conductive layers on the front and rear surfaces and conductive layer in the inner layer so as to achieve electric connection through via holes,

 said multilayer printed wiring board having the power source through holes described in claim 12 .

Claim 15 (withdrawn): The multilayer printed wiring board according to claim 9 wherein assuming that the sum of the thicknesses of the power source conductive layers in said multilayer core substrate is $\alpha 1$ and the thickness of the conductive layer on the interlayer insulation layer is $\alpha 2$, the relation of $\alpha 2 < \alpha 1 \leq 0.02\alpha 2$ exists.

Claim 16 (withdrawn): The multilayer printed wiring board according to claim 15 wherein said $\alpha 1$ is in a relation of $1.2\alpha 2 \leq \alpha 1 \leq 0.02\alpha 2$.

Claim 17 (withdrawn): The multilayer printed wiring board according to claim 9 wherein the conductive layers on the front and rear surfaces of said multilayer core substrate are power source conductive layers or grounding conductive layers.

Claim 18 (withdrawn): The multilayer printed wiring board according to claim 9 wherein said multilayer core substrate has a thick conductive layer in the inner layer and thin conductive layers on the front and rear surfaces.

Claim 19 (withdrawn): The multilayer printed wiring board according to claim 9 wherein the conductive layer of the inner layer in said multilayer core substrate is composed of two or more layers.

Claim 20 (withdrawn): The multilayer printed wiring board according to claim 9 wherein a capacitor is mounted on the surface thereof.

Claim 21 (withdrawn): A multilayer printed wiring board in which interlayer insulation layer and conductive layer are formed on a multilayer core substrate composed of three or more layers, having a plurality of through holes for connecting the front and rear

surfaces and conductive layers on the front and rear surfaces and conductive layer in the inner layer so as to achieve electric connection through via holes,

 said a plurality of through holes being composed of a plurality of power source through holes, a plurality of grounding through holes and a plurality of signal through holes connected electrically to a power source circuit or a grounding circuit or a signal circuit of an IC chip,

 when said power source through holes pass through the grounding conductive layer of the inner layer in the multilayer core substrate, of the plurality of power source through holes, part of the power source through hole just below the IC having no conductive circuit extending from the power source through hole in the grounding conductive layer.

Claim 22 (withdrawn): A multilayer printed wiring board in which interlayer insulation layer and conductive layer are formed on multilayer core substrate composed of three or more layers, having a plurality of through holes for connecting the front surface with the rear surface and conductive layers on the front and rear surfaces and conductive layer in the inner layer so as to achieve electric connection through via holes,

 said a plurality of through holes being composed of a plurality of power source through holes, a plurality of grounding through holes and a plurality of signal through holes connected electrically to a power source circuit or a grounding circuit or a signal circuit of an IC chip,

 when said grounding through holes pass through the power source conductive layer of the inner layer in the multilayer core substrate, of the plurality of grounding through holes, part of the grounding through hole just below the IC having no conductive circuit extending from the grounding through hole in the grounding conductive layer.

Claim 23 (withdrawn): A multilayer printed wiring board in which interlayer insulation layer and conductive layer are formed on a multilayer core substrate composed of

four or more layers, having a plurality of through holes for connecting the front and rear surfaces and conductive layers on the front and rear surfaces and conductive layer in the inner layer so as to achieve electric connection through via holes,

 said multilayer printed wiring board having the power source through holes described in claim 21 .

Claim 24 (withdrawn): The multilayer printed wiring board according to claim 11 wherein the through holes just below the IC are disposed in the form of a grid or in a staggered fashion.

Claim 25 (withdrawn): The multilayer printed wiring board according to claim 24 wherein the power source through holes and grounding through holes just below the IC are disposed alternately.

Claim 26 (withdrawn): The multilayer printed wiring board according to claim 14 wherein the power source through hole having no conductive circuit extending from the power source through hole in the grounding conductive layer and the grounding through hole having no conductive circuit extending from the grounding through hole in the power source conductive layer are disposed in the form of a grid or in the staggered fashion just below the IC.

Claim 27 (withdrawn): The multilayer printed wiring board according to claim 26 wherein the power source through hole having no conductive circuit extending from the power source through hole in the grounding conductive layer and the grounding through hole having no conductive circuit extending from the grounding through hole in the power source conductive layer are disposed alternately.

Claim 28 (withdrawn): The multilayer printed wiring board according to claim 23 wherein the power source through hole having no conductive circuit extending from the power source through hole in the grounding conductive layer and the grounding through hole

having no conductive circuit extending from the grounding through hole in the power source conductive layer are disposed in the form of a grid or in the staggered fashion just below the IC.

Claim 29 (withdrawn): The multilayer printed wiring board according to claim 28 wherein the power source through hole having no conductive circuit extending from the power source through hole in the grounding conductive layer and the grounding through hole having no conductive circuit extending from the grounding through hole in the power source conductive layer are disposed alternately.